TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSVI)

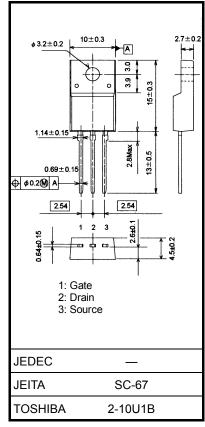
2SK3569

Switching Regulator Applications

- Low drain-source ON resistance: $RDS(ON) = 0.54 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 8.5S$ (typ.)
- Low leakage current: $I_{DSS} = 100 \ \mu A (V_{DS} = 600 \text{ V})$
- Enhancement mode: $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Characteristics Symbol Rating Unit Drain-source voltage 600 ۷ VDSS 600 v Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$) VDGR V Gate-source voltage ±30 VGSS DC (Note 1) I_D 10 Drain current Α Pulse (t = 1 ms) 40 IDP (Note 1) Drain power dissipation (Tc = 25°C) 45 w P_D Single pulse avalanche energy E_{AS} 363 mJ (Note 2) Avalanche current А I_{AR} 10 4.5 Repetitive avalanche energy (Note 3) E_{AR} mJ °C Channel temperature T_{ch} 150 °C Storage temperature range Tstg -55~150





Weight : 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

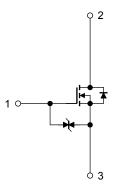
Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W	
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_DD = 90 V, T_ch = 25 $^\circ\text{C}(\text{initial}),$ L = 6.36 mH, I_AR = 10 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.



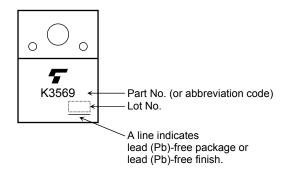
Electrical Characteristics (Ta = 25°C)

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±10	μA
Gate-source breakdown voltage		V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30		_	V
Drain cut-off curr	ent	I _{DSS}	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600		_	V
Gate threshold v	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON	resistance	R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$	_	0.54	0.75	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$	0.7	8.5	_	S
Input capacitance	e	C _{iss}		_	1500	_	
Reverse transfer capacitance		C _{rss}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz		15		pF
Output capacitance		C _{oss}		_	180	_	
Switching time	Rise time	tr	V_{GS} $0 V$ V_{GS} $0 V$ V_{GS} $0 V$ 0	_	22		- ns
	Turn-on time	t _{on}		_	50	_	
	Fall time	t _f		_	36	_	
	Turn-off time	t _{off}	Duty \leq 1%, t _w = 10 μ s		180		
Total gate charge		Qg		_	42	_	
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		23		nC
Gate-drain charge		Q _{gd}			19		

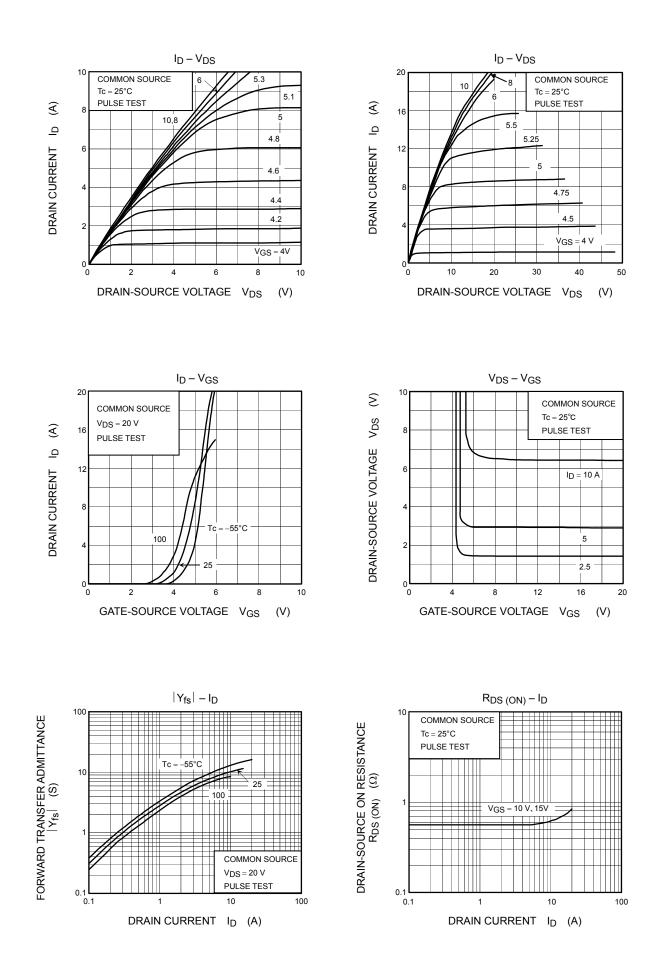
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	10	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_		40	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 10 A, V _{GS} = 0 V,	_	1300	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs	_	16	_	μC

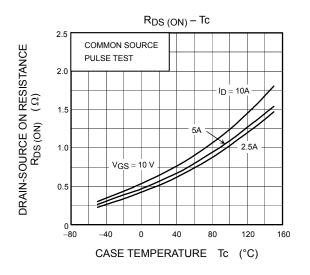
Marking

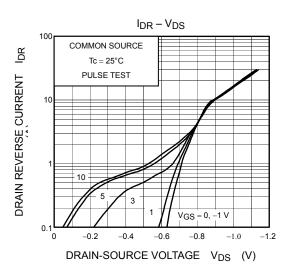


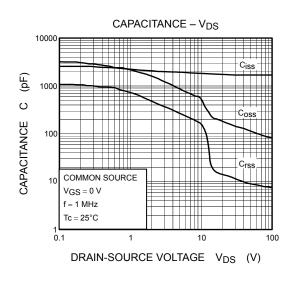
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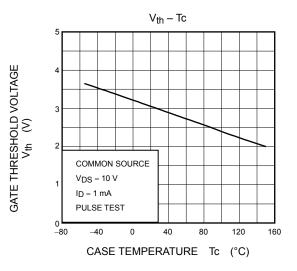


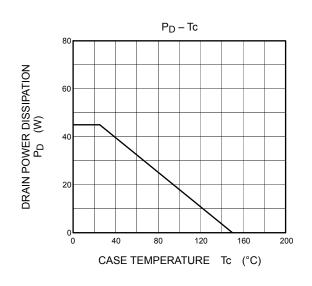
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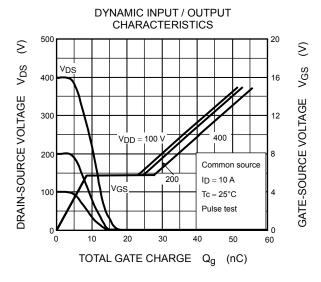


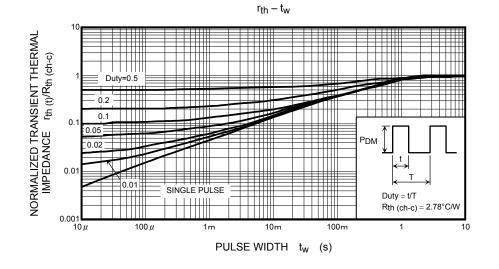




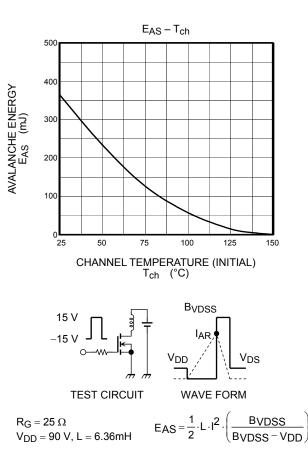








SAFE OPERATING AREA 100 ID max (PULSED) * 100 μs ID max (CONTINUOUS) € 10 DRAIN CURRENT ID DC OPERATION $Tc = 25^{\circ}C$ 0.1 **※** SINGLE NONREPETITIVE PULSE Tc=25°C CURVES MUST BE DERATED LINEARLY WITH INCREASE IN VDSS max TEMPERATURE 0.01 10 100 1000 1 DRAIN-SOURCE VOLTAGE VDS (V)



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20070701-EN

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